

ABSTRACT OF THE DISCLOSURE

An exposure apparatus comprises an irradiation optical system for irradiating a pattern formed on an original plate with light emitted from a light source, a projection optical system for projecting a light image from the pattern onto a substrate, a drivable substrate stage for mounting the substrate, and a light absorber disposed on the substrate stage, wherein the light absorber is disposed on the substrate stage by a thermal insulating layer and/or a cooling unit. Thus, an exposure apparatus can be provided which performs exposure of a wafer without being influenced by adverse effects such as thermal deformation of units such as a wafer stage or the like due to exposure process other than exposure of the wafer, such as pre-exposure.